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FOR IMMEDIATE RELEASE

Hymite A/S Announces Innovative Silicon-Based Packaging Solution for High-Volume Production of High-Brightness LEDs at Low Cost

Proven IC-Style Production and Assembly Meets Demanding Thermal and Size Requirements

COPENHAGEN and DALLAS, February 12, 2007 - Danish-German technology company Hymite A/S, an innovative supplier of advanced wafer level packaging products for electronics, micromechanical and optoelectronics components, today announced HyLED™, a silicon-based packaging solution for high-brightness light emitting diodes (HB LEDs) in multiple markets.

HyLED™ enables component miniaturization, cost-effective manufacture and deployment of HB LED products across key industries where demand is high, from general lighting to mobile electronics, automotive lighting and panel backlighting.

A major European customer, which develops and produces high-performance digital light sources, is using HyLED™ for its cutting-edge light source product and has achieved significant package miniaturization and power efficiencies.

“The primary challenge for HB LED manufacturers has been miniaturization and mass production of the components to meet market needs, while addressing unique thermal requirements and reducing the cost per lumen,” said Jochen Kuhmann, CTO and founder, Hymite A/S. “HyLED™ silicon packaging overcomes these obstacles through wafer-scale production and assembly. We see a major market opportunity for significant enhancement of HB LEDs for widespread applications and markets.”

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The technology behind HyLED™ is silicon wafers and batch micromachining/metallization processes delivering package size reductions of up to 4x. Proven IC-style automated manufacturing processes increase throughputs and yields for a lower cost per unit. The option of wafer level assembly and testing for the end-customer introduces huge cost benefits in this high-volume price sensitive consumer sector.

Additionally, silicon has excellent inherent thermal management characteristics. Hymite's engineers provide optimized designs alleviating thermal and thermo-mechanical stress for excellent performance, even for the most demanding operation conditions. Unlike other package technologies, the micromachined LED cavity acts as a reflector, thermal conductor and reservoir for silicone.

About Hymite

Hymite is a technology leader of silicon-based wafer level packaging for MEMS, electronics and optoelectronics products. The products and technologies Hymite offers significantly reduce cost/performance ratio for packaging of components and systems through innovative designs, component integration and wafer-level assembly and testing. Further information can be obtained from the company's website at www.hymite.com.

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